# 502776785 04/22/2014

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT2823380

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
JOON-WOO KIM	03/27/2014

#### **RECEIVING PARTY DATA**

Name:	SK HYNIX INC.	
Street Address:	2091, GYEONGCHUNG-DAERO, BUBAL-EUB	
City:	ICHEON-SI GYEONGGI-DO	
State/Country:	KOREA, REPUBLIC OF	

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14258206

#### **CORRESPONDENCE DATA**

**Fax Number:** (630)908-7653

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via

US Mail.

**Phone:** 6309087652

**Email:** uspto.actions@wpapat.com

Correspondent Name: WILLIAM PARK & ASSOCIATES PATENT LTD.

Address Line 1: 930 N. YORK ROAD, SUITE 201
Address Line 4: HINSDALE, ILLINOIS 60521

ATTORNEY DOCKET NUMBER:	PA1607-0	
NAME OF SUBMITTER:	WOOCHOON WILLIAM PARK	
SIGNATURE:	/Woochoon William Park/	
<b>DATE SIGNED:</b> 04/22/2014		
	This document serves as an Oath/Declaration (37 CFR 1.63).	

**Total Attachments: 1** 

source=PA1607-0\_Declaration\_Assignment#page1.tif

PATENT 502776785 REEL: 032732 FRAME: 0886

### DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention	SEMICONDUCTOR DEVICE		
Declaration	As the below named inventor(s), I hereby declare that  The declaration is directed to  The attached application, or  United States application or PCT international application number filled on  The above-identified application was made or authorized to be made by me. I believe that I am the original or an original joint inventor of a claimed invention in the application. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by line or imprisonment of not more than five (5) years or both.		
Assignment	NOW, THEREFORE, in consideration of the sum of one dollar (\$1), the receipt whereof is enknowledge, and other good and valuable consideration, it, by these presents do sell, assign and transfer unto said assignee(s)  SK Hynix Inc.  2091, Gyeongchung-daero, Bubel-bub, Icheon-si, Gyeonggi-do, Republic of Korea and the heirs, successors, assigns and legal representatives of the assignee(s) the full and exclusive right to the said invention in the United States and in its territorial possessions and in any and all foreign countries any and all improvements thereof, the entire rights, title and interest in and fo any and all Patents which may be granted therefore in the United States. I histely authorize and request the Director of the U.S. Patent and Trademark Office to issue said United States Patent to said assignee(s), of the entire right, title, and interest in and to the same, for his sole use and for the use of his legal representatives to the full and of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.  I agree promptly upon request of the assignee(s), its heirs, successors, assigns and legal representatives of the assignee(s) to communicate any facts known to it respecting the patent and the invention set forth therein, and to execute and deliver without further compensation any power of attorney, Assignment application, whether original continuation, divisional or reinsue, or other papers that may be necessary.  I hereby covenant that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.  I further covenant that no assignment and accessible to me and will tosiffy as to the same in any litigation related thereto and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to me and will tosiffy as to the same in any litigation related thereto and will promptly execute		
Legal Name Of Inventor	Inventor Name (First Middle LAST)	Joon-Wae KIM	
	Inventor Signature  Date	<i>  [2014]</i>   2014   03 21	

Page 1

[ ] A total of \_\_\_supplemental sheet(s) are attached hereto for additional inventors, if any

**REEL: 032732 FRAME: 0887**